



Material Content Data Sheet



Sales Product Name		TLS208D1LDV		Issued		1. August 2018		
MA#		MA001338862						
Package		PG-TSON-10-2		Weight*		31.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.453	4.56	4.56	45581	45581
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		416	
	non noble metal	iron	7439-89-6	0.265	0.83		8322	
wire	non noble metal	copper	7440-50-8	10.773	33.79	34.67	337896	346738
	non noble metal	copper	7440-50-8	0.047	0.15	0.15	1466	1466
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1147
plastics	plastics	epoxy resin	-	1.883	5.90		59049	
	inorganic material	silicondioxide	60676-86-0	16.358	51.32	57.33	513095	573291
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11608	11608
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2016	2016
glue	plastics	epoxy resin	-	0.154	0.48		4825	
	noble metal	silver	7440-22-4	0.461	1.45	1.93	14475	19300
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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